



Features

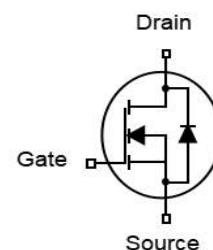
- N-Channel
- Low Gate Charge
- Green Device Available
- 100% EAS Tested

| | | |
|--|-----|------------------|
| V_{DS} | 60 | V |
| $R_{DS(on),TYP}$ @ $V_{GS}=10\text{ V}$ | 8.5 | $\text{m}\Omega$ |
| $R_{DS(on),TYP}$ @ $V_{GS}=4.5\text{ V}$ | 12 | $\text{m}\Omega$ |
| I_D | 30 | A |

DFN3x3



| Part ID | Package Type | Marking | Packing |
|------------|--------------|------------|--------------|
| ZTG080N06Q | DFN3x3 | ZTG080N06Q | 5000pcs/Reel |



Absolute Maximum Ratings $T_A=25^\circ\text{C}$, unless otherwise specified

| Symbol | Parameter | Rating | Unit | |
|--|---|-------------------------|---------------------------|---|
| Common Ratings (Tc=25°C Unless Otherwise Noted) | | | | |
| V_{GS} | Gate-Source Voltage | ± 20 | V | |
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage | 60 | V | |
| T_J | Maximum Junction Temperature | 150 | $^\circ\text{C}$ | |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ\text{C}$ | |
| I_{DM} | Drain Current-Continuous@ Current-Pulsed (Note 2) | $T_c=25^\circ\text{C}$ | 120 | A |
| Mounted on Large Heat Sink | | | | |
| I_D | Drain Current-Continuous (Note 1) | $T_c=25^\circ\text{C}$ | 30 | A |
| | | $T_c=100^\circ\text{C}$ | 20 | A |
| P_D | Maximum Power Dissipation (Note 4) | 21 | W | |
| $R_{\theta JC}$ | Thermal Resistance-Junction to Case | 6 | $^\circ\text{C}/\text{W}$ | |
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient (Note 1) | 60 | $^\circ\text{C}/\text{W}$ | |
| Drain-Source Avalanche Ratings | | | | |
| EAS | Avalanche Energy, Single Pulsed (Note 3) | 54 | mJ | |



Electrical Characteristics (T_J=25°C unless otherwise noted)

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|----------------------------------|--|-----|-----|------|------|
| Static Electrical Characteristics @ T_J=25°C (unless otherwise stated) | | | | | | |
| V(BR)DSS | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 60 | -- | -- | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =48V, V _{GS} =0V | -- | -- | 1 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{GS} =±20V, V _{DS} =0V | -- | -- | ±100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 1.4 | 1.8 | 2.4 | V |
| R _{D(on)} | Drain-Source On-State Resistance | V _{GS} =10V, I _D =13.5A | -- | 8.5 | 9.5 | mΩ |
| R _{D(on)} | Drain-Source On-State Resistance | V _{GS} =4.5V, I _D =11.5A | -- | 12 | 16 | mΩ |

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)

| | | | | | | |
|------------------|------------------------------|--|----|------|----|----|
| C _{iss} | Input Capacitance | V _{DS} =30V, V _{GS} =0V, f=1MHz | -- | 933 | -- | pF |
| C _{oss} | Output Capacitance | | -- | 272 | -- | pF |
| C _{rss} | Reverse Transfer Capacitance | | -- | 26 | -- | pF |
| R _g | Gate Resistance | f=1MHz | -- | 1.6 | -- | Ω |
| Q _g | Total Gate Charge | V _{DS} =30V, I _D =12A, V _{GS} =10V | -- | 15.8 | -- | nC |
| Q _{gs} | Gate-Source Charge | | -- | 3.1 | -- | nC |
| Q _{gd} | Gate-Drain Charge | | -- | 4.4 | -- | nC |

Switching Characteristics

| | | | | | | |
|---------------------|---------------------|--|----|-----|----|----|
| T _{d(on)} | Turn-on Delay Time | V _{DD} =30V, I _D =12A, R _G =3.3Ω, V _{GS} =10V | -- | 5.8 | -- | ns |
| T _r | Turn-on Rise Time | | -- | 3.5 | -- | ns |
| T _{d(off)} | Turn-Off Delay Time | | -- | 26 | -- | ns |
| T _f | Turn-Off Fall Time | | -- | 3.2 | -- | ns |

Source- Drain Diode Characteristics@ T_J = 25°C (unless otherwise stated)

| | | | | | | |
|-----------------|----------------------------------|---|----|----|-----|---|
| I _S | Diode Forward Current (Note 1,5) | | -- | -- | 30 | A |
| V _{SD} | Forward on voltage (Note 2) | I _S =1A, V _{GS} =0V | -- | -- | 1.2 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. Single pulse width limited by junction temperature T_{J(MAX)}=150°C.
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=33A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

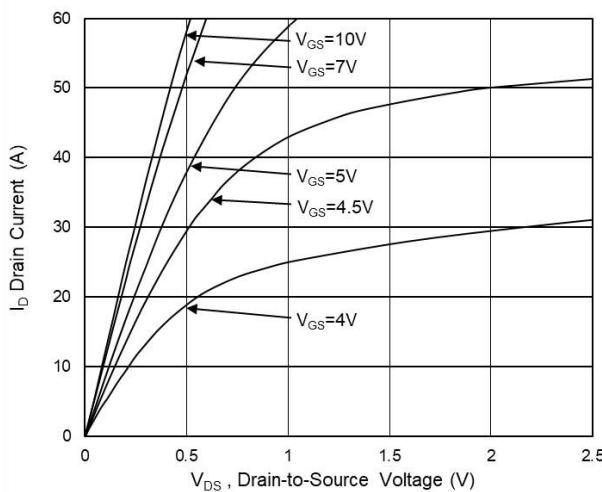


Fig.1 Typical Output Characteristics

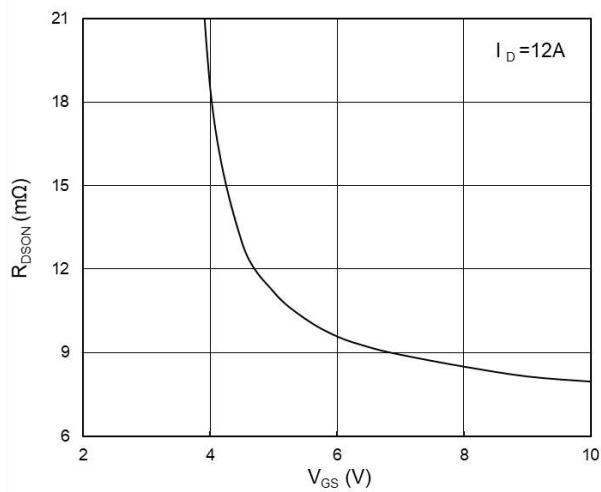


Fig.4 On-Resistance vs G-S Voltage

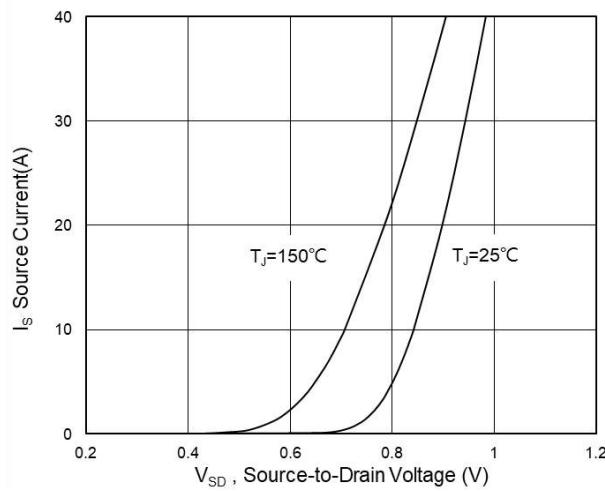


Fig.2 Source Drain Forward Characteristics

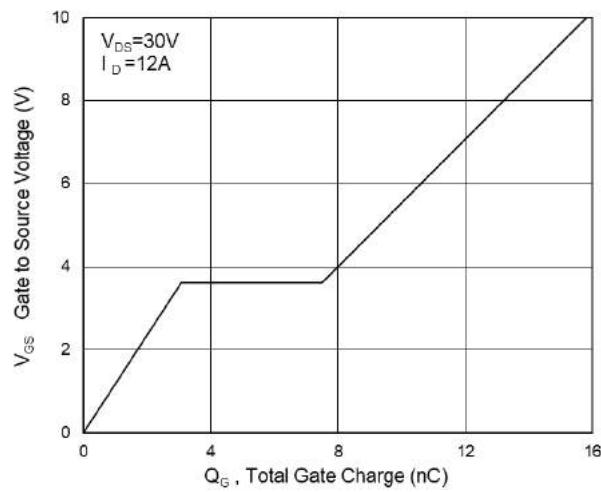


Fig.5 Gate-Charge Characteristics

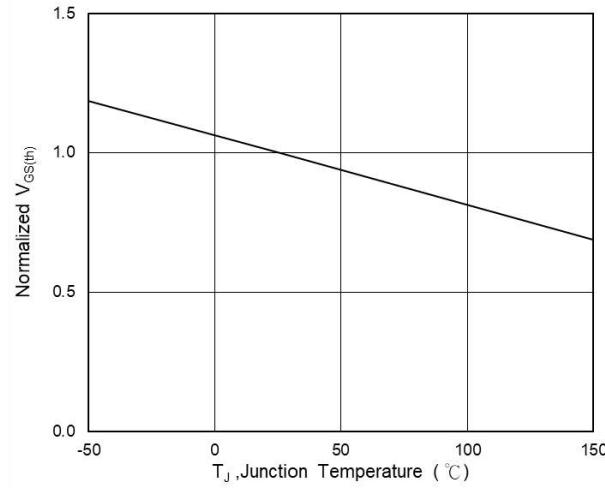


Fig.3 Normalized $V_{GS(th)}$ vs T_J

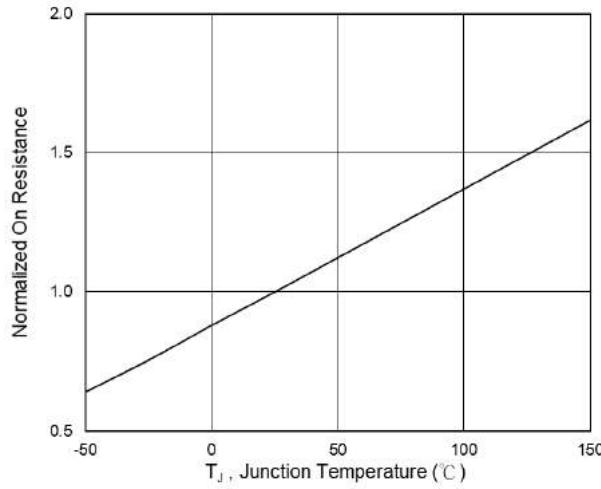


Fig.6 Normalized $R_{DS(on)}$ vs T_J

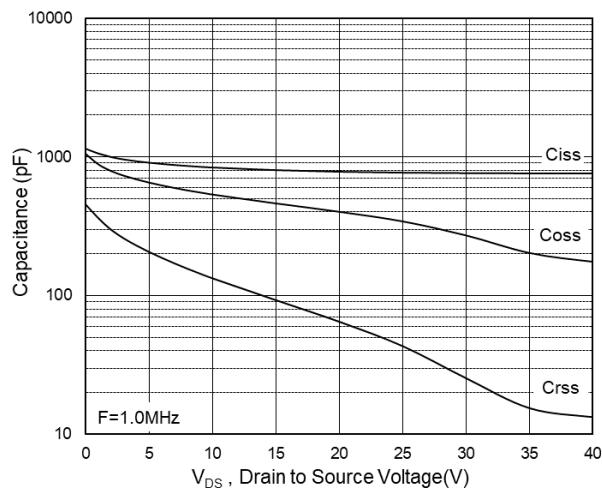


Fig.7 Capacitance

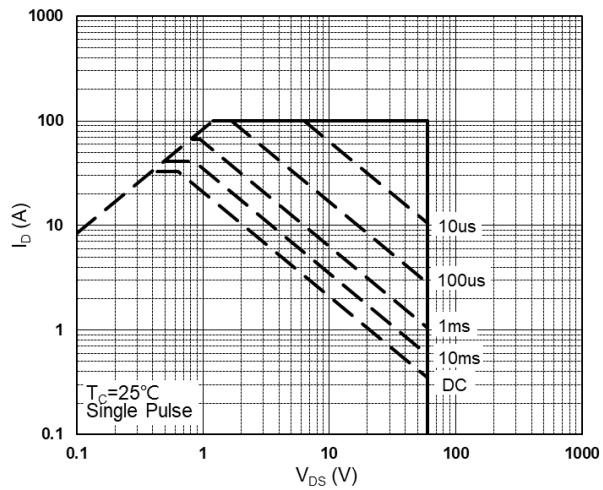


Fig.8 Safe Operating Area

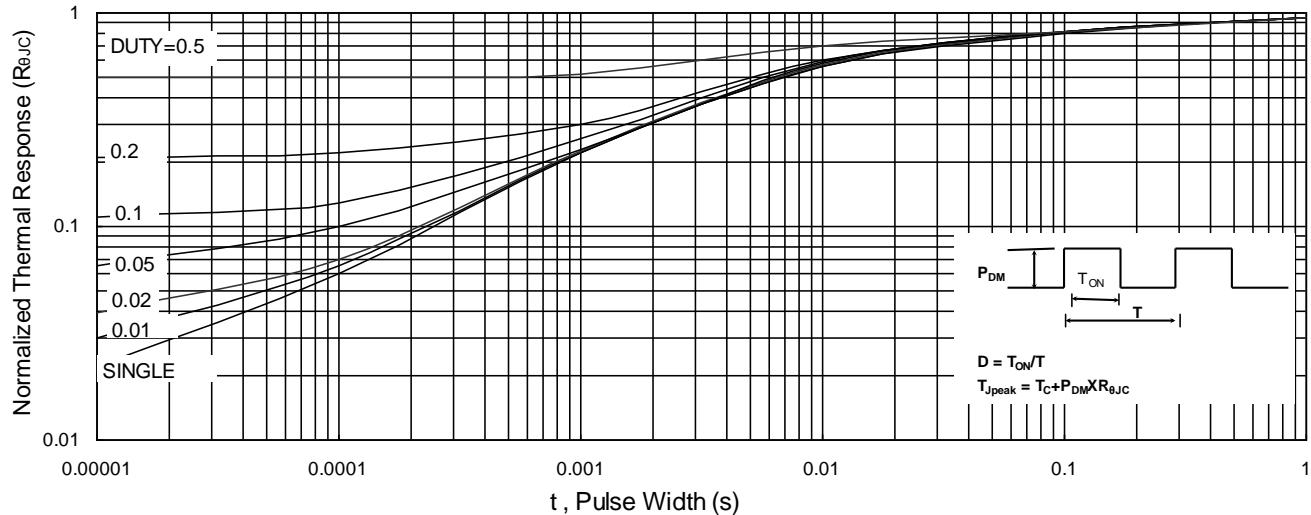
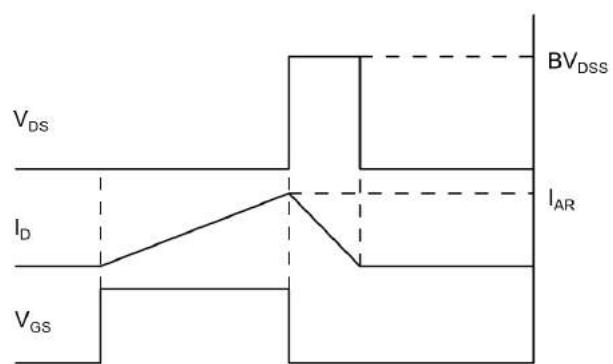
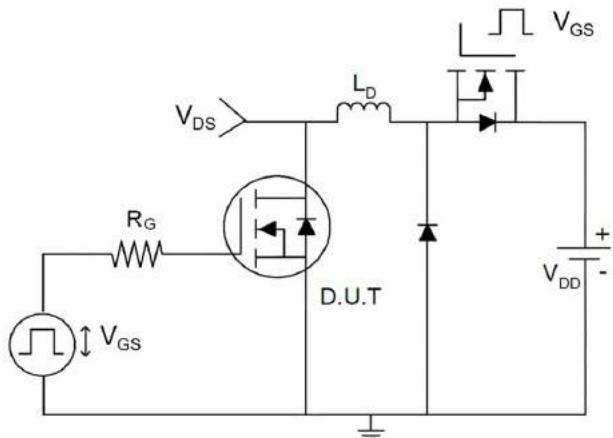


Fig.9 Normalized Maximum Transient Thermal Impedance

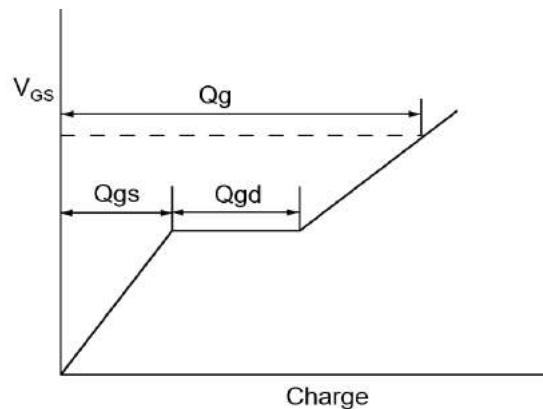
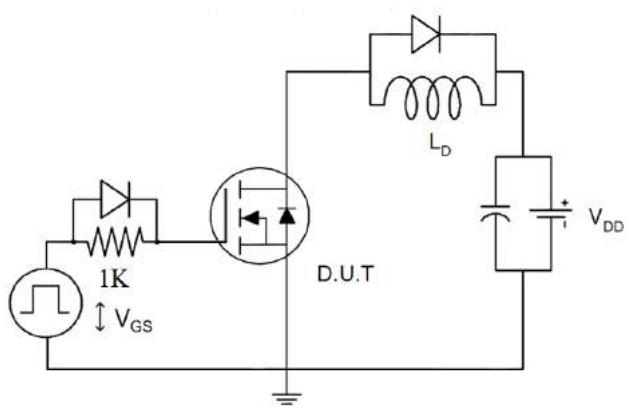


Test Circuit

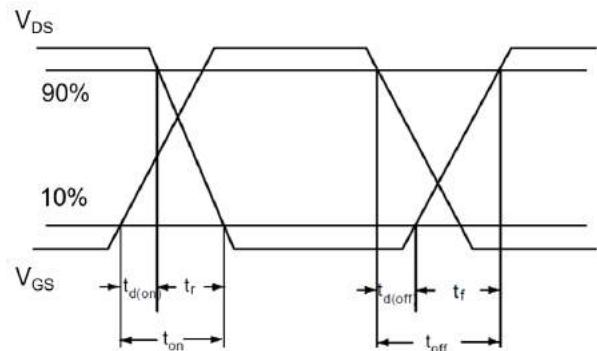
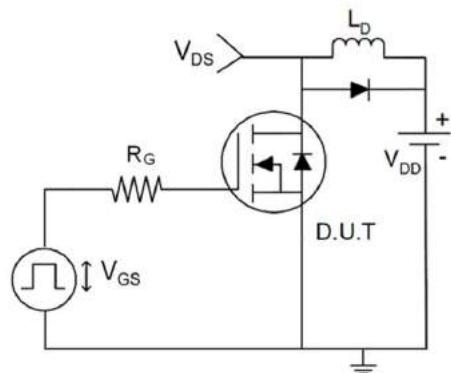
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit

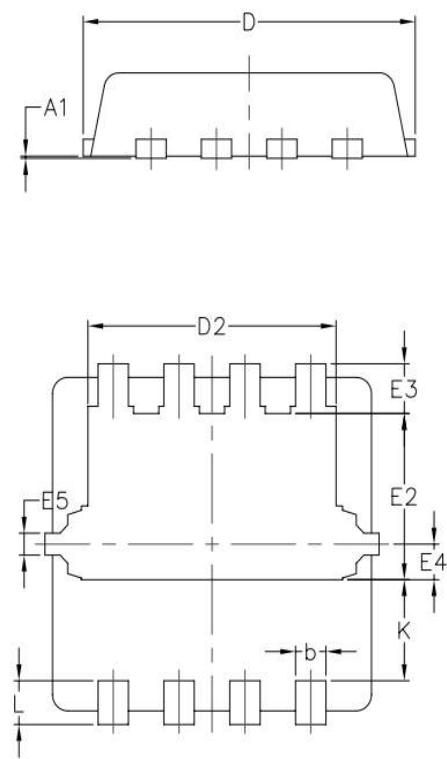
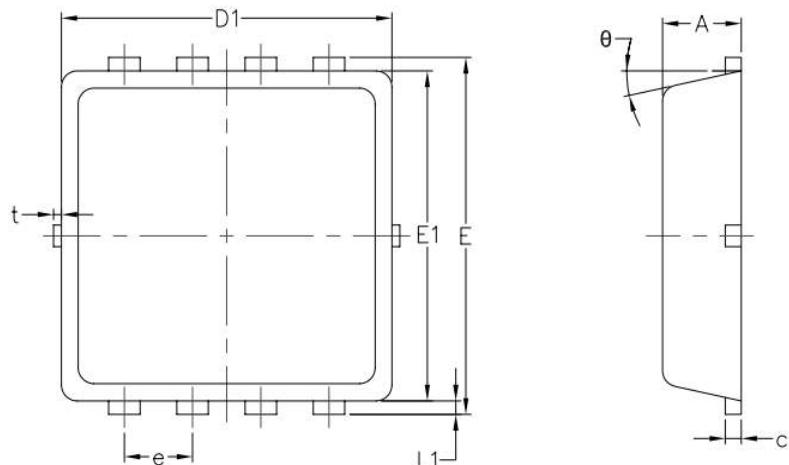


3) Switch Time Test Circuit





DFN3x3-8L Package Information



| SYMBOL | COMMON | | |
|--------|--------|-------|------|
| | MM | | |
| | MIN | NOM | MAX |
| A | 0.70 | 0.75 | 0.85 |
| A1 | / | / | 0.05 |
| b | 0.20 | 0.30 | 0.40 |
| c | 0.10 | 0.152 | 0.25 |
| D | 3.15 | 3.30 | 3.45 |
| D1 | 3.00 | 3.15 | 3.25 |
| D2 | 2.29 | 2.45 | 2.65 |
| E | 3.15 | 3.30 | 3.45 |
| E1 | 2.90 | 3.05 | 3.20 |
| E2 | 1.32 | 1.52 | 1.72 |
| E3 | 0.28 | 0.46 | 0.65 |
| E4 | 0.18 | 0.33 | 0.48 |
| E5 | 0.10 | 0.20 | 0.30 |
| e | 0.60 | 0.65 | 0.70 |
| K | 0.78 | 0.93 | 1.13 |
| L | 0.30 | 0.40 | 0.50 |
| L1 | 0.06 | 0.125 | 0.20 |
| t | 0 | 0.075 | 0.13 |
| θ | 10° | 12° | 14° |

Customer Service

Sales and Service:

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